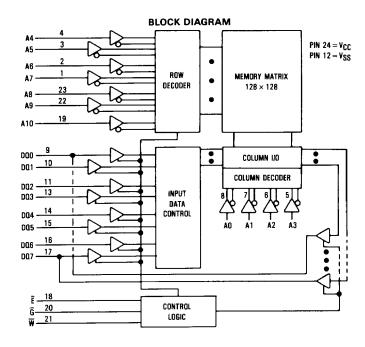
## Fast 16K Bit Static RAM

The MCM2016H is a 16,384 bit static random access memory organized as 2048 words by 8 bits, fabricated using Motorola's high-performance silicon-gate MOS (HMOS) technology. It uses an innovative design approach which combines the ease-of-use features of fully static operation (no external clocks or timing strobes required) with the reduced standby power dissipation associated with clocked memories. To the user this means low standby power dissipation without the need for address setup and hold times, nor reduced data rates due to cycle times that are longer than access times. Perfect for cache and sub-100 ns buffer memory systems, this high speed static RAM is intended for applications that demand superior performance and reliability.

Chip enable  $(\overline{E})$  controls the power-down feature. It is not a clock but rather a chip control that affects power consumption. In less than a cycle time after  $\overline{E}$  goes high, the part automatically reduces its power requirements and remains in this low-power standby mode as long as  $\overline{E}$  remains high. This feature provides significant system-level power savings.

The MCM2016H is in a 24-pin dual-in-line 300 mil wide plastic package with the industry standard JEDEC approved pinout.

- Single +5 V Operation, ±10%
- Fully Static: No Clock or Timing Strobe Required
- Fast Access Time: MCM2016H-45 = 45 ns (Maximum)
  MCM2016H-55 = 55 ns (Maximum)
  MCM2016H-70 = 70 ns (Maximum)
- Power Supply Current: 135 mA Maximum (Active)
  20 mA Maximum (Standby)
- Three-State Output



### MCM2016H



N PACKAGE PLASTIC CASE 724

PIN	ASSIGN	MI	ENT
A7 [	1 •	24	v <sub>cc</sub>
А6 Д	2	23	] A8
A5 [	3	22	] A9
A4 [	4	21	D₩
АЗ [	5	20	þē
A2 E	6	19	DA10
A1 [	7	18	þē
AD E	8	17	007
000 £	9	16	D 006
DQ1 <b>E</b>	10	15	0025
DQ2 <b>E</b>	11	14	] DQ4
v <sub>ss</sub> e	12	13	<b>D</b> DQ3

PIN NAMES									
	Address Inpu								
DQ0-D	Data Input/Outpu	ιt							
₩	Write Enable	le							
G	Output Enabl	le							
	Chip Enable								
	+ 5 V Power Suppl								
Vss .	Groun	d							

#### **MODE SELECTION**

Mode	Ē	G	w	V <sub>CC</sub> Current	DQ
Standby	Н	х	х	<sup>I</sup> SB	High Z
Read	L	L	н	<sup>1</sup> cc	Q
Write Cycle	L	Х	L	¹cc	D

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

#### **ABSOLUTE MAXIMUM RATINGS (See Note)**

Rating	Symbol	Value	Unit
Power Supply Voltage	Vcc	-0.5 to +7.0	V
Voltage on Any Pin With Respect to VSS	V <sub>in</sub> , V <sub>out</sub>	-0.5 to +7.0	V
DC Output Current	lout	± 20	mA
Power Dissipation	PD	1.1	Watt
Temperature Under Bias	T <sub>bias</sub>	- 10 to +80	°C
Operating Temperature Range	TA	0 to +70	°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPERATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

#### DC OPERATING CONDITIONS AND CHARACTERISTICS

(V<sub>CC</sub> = 5.0 V  $\pm$  10%, T<sub>A</sub> = 0 to 70°C, Unless Otherwise Noted)

#### **RECOMMENDED OPERATING CONDITIONS**

Parameter	Symbol	Min	Тур	Max	Unit
Supply Voltage (Operating Voltage Range)	Vcc	4.5	5.0	5.5	V
	Vss	0	0	0	V
Input Voltage (50 ns Maximum Address Rise and Fall Times, while the chip is selected)	V <sub>IH</sub>	2.2	3.0	6.0	v
	VIL	-0.5*	0	0.8	V

<sup>\*</sup>The device will withstand undershoots to the -2.5 volt level with a maximum pulse width of 50 ns. This is periodically sampled rather than 100% tested.

#### DC CHARACTERISTICS

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (V <sub>CC</sub> =5.5 V, V <sub>in</sub> =GND to V <sub>CC</sub> )	likg(I)	- 1.0	1.0	μА
Output Leakage Current ( $\overline{E} = V_{IH}$ or $\overline{G} = V_{IH}$ , $V_{I/O} = GND$ to $V_{CC}$ )	l <sub>lkg(O)</sub>	- 1.0	1.0	μА
Operating Power Supply Current (E=V <sub>IL</sub> , I <sub>I/O</sub> =0 mA)	lcc	_	135	mA
Standby Power Supply Current ( $\overline{E} = V_{1H}$ )	ISB		20	mA
Output Low Voltage (I <sub>OL</sub> = 8.0 mA)	VOL	_	0.4	V
Output High Voltage (I <sub>OH</sub> = ~4.0 mA)	Voн	2.4	_	v

#### CAPACITANCE (f = 1.0 MHz, TA = 25°C, Periodically Sampled Rather Than 100% Tested)

Ch	aracteristic	Symbol	Тур	Max	Unit
Input Capacitance	All Inputs Except $\overline{E}$ and DQ $\overline{E}$	C <sub>in</sub>	3 5	5 7	pF
I/O Capacitance	DQ	C <sub>I/O</sub>	5	7	pF

#### **AC OPERATING CONDITIONS AND CHARACTERISTICS**

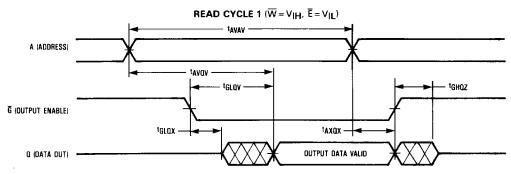
 $(V_{CC} = 5 \text{ V } \pm 10\%, T_A = 0 \text{ to } +70^{\circ}\text{C}, \text{ Unless Otherwise Noted})$ 

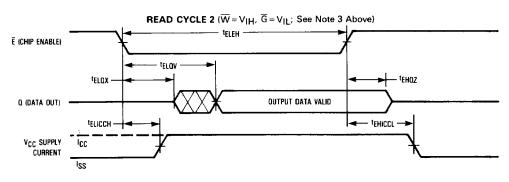
#### **READ CYCLE** (See Note 1)

Downston	Syn	nboł	MCM2016H-45		MCM2016H-55		MCM2016H-70			
Parameter	Standard	Alternate	Min	Max	Min	Max	Min	Max	Units	Notes
Address Valid to Address Valid (Read Cycle Time)	tAVAV	tRC	45	_	55	_	70	_	ns	
Address Valid to Output Valid (Address Access Time)	tAVQV	tAC	_	45	_	55	_	70	ns	
Chip Enable Low to Chip Enable High (Read Cycle Time)	tELEH	<sup>t</sup> RC	45	-	55	_	70	_	ns	
Chip Enable Low to Output Valid (Chip Enable Access Time)	tELQV	†ACS	_	45	-	55	_	70	ns	
Output Enable Low to Output Valid (Output Enable Access Time)	1GLQV	<sup>t</sup> OE	_	20	_	25	_	30	ns	
Chip Enable Low to Output Invalid (Chip Enable to Output Active)	tELQX	<sup>t</sup> CLZ	5	-	5	_	5	-	ns	2
Chip Enable High to Output High Z (Chip Disable to Output Disable)	tEHQZ	tCHZ	0	20	0	20	0	20	ns	2
Output Enable Low to Output Invalid (Output Enable to Output Active)	tGLQX	tOLZ	0	-	0		0	-	ns	2
Output Enable High to Output High Z (Output Disable to Output Disable)	tGHQZ	tOHZ	0	20	0	20	0	20	ns	2
Address Invalid to Output Invalid (Output Hold Time)	tAXQX	tOH	5	-	5	-	5	_	ns	
Chip Enable Low to Power Up	†ELICCH	tPU	0	_	0	_	0	_	ns	
Chip Enable High to Power Down	†EHICCL	tPD	_	20	-	20	_	20	ns	

#### NOTES:

- Transition time specification applies for all input signals. In addition to meeting the transition rate specification, all input signals must transition between V<sub>IL</sub> and V<sub>IH</sub> (or between V<sub>IH</sub> and V<sub>IL</sub>) in a monotonic manner.
- 2. Transition is measured ± 200 mV from the steady state output voltage with the output loading specified in Figure 1.
- 3. In read cycle 2, all addresses are valid prior to or coincident with chip enable (E) transition low.





#### WRITE CYCLE (See Notes 1 and 2)

	Symbol		MCM2016H-45		MCM2016H-55		MCM2016H-70			
Parameter	Standard	Alternate	Min	Max	Min	Max	Min	Max	Units	Notes
Address Valid to Address Valid (Write Cycle Time)	†AVAV	twc	45		55		70	_	ns	
Chip Enable Low to Write High (Chip Enable to End of Write)	<sup>†</sup> ELWH	tEW	40	-	50	-	65	-	ns	
Address Valid to Chip Enable Low (Address Setup to Chip Enable)	<sup>†</sup> AVEL	<sup>t</sup> AS	0	_	0	_	0	-	ns	
Address Valid to Write Low (Address Setup to Write)	†AVWL	†AS	0	_	0	_	0	-	ns	
Address Valid to Write High	†AVWH	tAW	40		50		65	-	ns	3
Write Low to Write High (Write Pulse Width)	tWLWH	twp	35		40		40	-	ns	
Write High to Address Don't Care (Address Hold After End of Write)	†WHAX	<sup>†</sup> WR	0	-	0	_	0	_	ns	4
Write High to Output Don't Care (Output Active After End of Write)	twhax	tWLZ	0	-	0	_	0	-	ns	5
Write Low to Output High Z (Write Enable to Output Disable)	tWLQZ	tWHZ	0	20	0	20	0	20	ns	5
Data Valid to Write High (Data Setup to End of Write)	tDVWH	†DS	20	-	25	-	30	-	ns	3
Write High to Data Don't Care (Data Hold After End of Write)	tWHDX	ţDH	0	_	0		0	_	ns	3, 5
Output Enable High to Output High Z	tGHOZ	toHZ	0	20	0	20	0	20	ns	

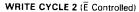
#### NOTES:

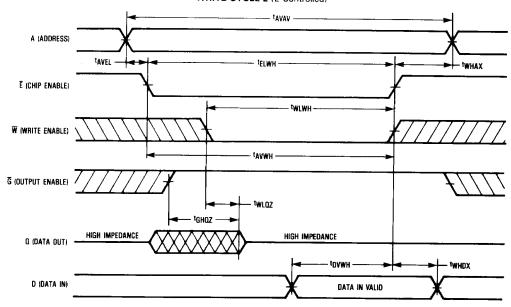
D (DATA IN)

- 1. Write enable (W) must be high during all address transitions.
- 2. If the chip enable (E) low transition occurs simultaneously with the write enable (W) transition, the output remains in a high impedance
- 3. Both chip enable (E) and write enable (W) must be active (low) to write data into the memory. Either signal can terminate the write cycle by going high. Data in setup and hold timing should be referenced to the rising edge of the signal that terminates the write.
- 4. twhax is measured from the earlier of, chip enable (E) or write enable (W) going high to the end of write cycle.
- 5. Output enable (G) can be either low or high during a write cycle. If chip enable (E) and G are both low during this period then the data input/output (DQ) pins are in the output state. Under these conditions input signals of opposite phase to the outputs must not be applied.

WRITE CYCLE 1 (W Controlled)

## - tavav A (ADDRESS) <sup>t</sup>ELWH E (CHIP ENABLE) **tWLWH** TAVWL W (WRITE ENABLE) - HWVA<sup>†</sup> G (OUTPUT ENABLE) · twLaz XDHW HIGH IMPEDANCE Q (DATA OUT) **tw**HDX DATA IN VALID





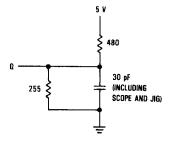
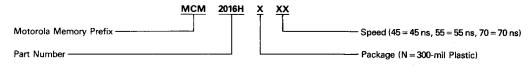


Figure 1. Output Load

# ORDERING INFORMATION (Order by Full Part Number)



Full Part Numbers - MCM2016HN45 MCM2016HN55 MCM2016HN70